1-4

L1 TOP CONDUCTOR - COPPER 0.035 MM
  * DIELECTRIC - PREPREG_2116 0.12 MM
  * DIELECTRIC - PREPREG_106 OR PREPREG_1080 0.06 MM
L2 L2 PLANE - COPPER 0.035 MM

TOTAL PREPREG 0.18 MM (+0.03/-0.01)

  * DIELECTRIC - FR-4 1.10 MM(+0.11/-0.11)

L3 L3 PLANE - COPPER 0.035 MM
  * DIELECTRIC - PREPREG_106 OR PREPREG_1080 0.06 MM
  * DIELECTRIC - PREPREG_2116 0.12 MM
L4 BOTTOM CONDUCTOR - COPPER 0.035 MM

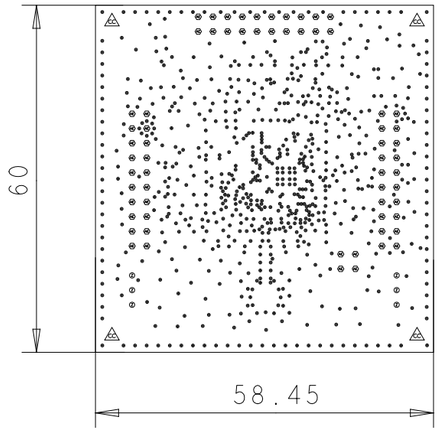
TOTAL PREPREG 0.18 MM (+0.03/-0.01)

DESIGN CROSS SECTION CHART

TOTAL THICKNESS 1.6 MM (+0.16/-0.16)

TOTAL THICKNESS is after press

FR-4: Er = 4.0-4.6



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	FINISHED_SIZE	DRILLED_SIZE	PLATED	QTY
•	0.2	-	PLATED	762
⊕	1.05	-	PLATED	6
⊕	1.05	-	PLATED	64
◬	3.2	-	PLATED	4

DESIGN INFORMATION

MIN. TRACK WIDTH: 0.15 mm
MIN. CLEARANCE: 0.15 mm
MIN. VIA PAD SIZE: 0.40 mm
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/-150 um, HOLES +/-80 um
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/-80 um

MATERIAL:
[X] FR-4 [ ] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 1.6mm +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [ ] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 30-40 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SILKSCREEN RESIST COLOR: [ ] GREEN [X] OTHER RED
[X] MATTE [ ] SEMI-GLOSS

SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-VO REQUIREMENTS.
PCB MUST BEAR THE UL94V-O UL REG. MATERIAL ID NUMBER: BOTTOM SILK
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [X] NONE [ ] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

TITLE: BP-CC140xP-x-FE

PROJECT NUMBER: MCU201

FILE NAME: BP-CC140xP-x-FE.brd

DESIGNER:	DATE:	REVISION:
DPM, SVGR	2026-09-04	A
SCALE: 1.00	ALLEGRO DESIGNER VERSION: 24.1	

	TEXAS INSTRUMENTS
	DRILL BP-CC140xP-x-FE Rev. A
	DATE: 2026-09-04

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